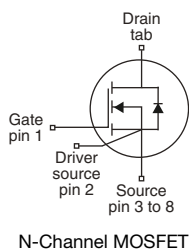
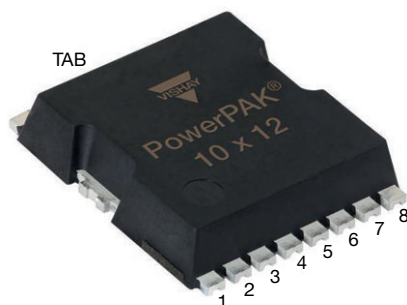


## E Series Power MOSFET

**PowerPAK® 10 x 12**


### FEATURES

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM)  $R_{DS(on)} \times Q_g$
- Low effective capacitance ( $C_{o(er)}$ )
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see [www.vishay.com/doc299912](http://www.vishay.com/doc299912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

### PRODUCT SUMMARY

$V_{DS}$ (V) at $T_J$ max.	700	
$R_{DS(on)}$ typ. ( $\Omega$ ) at 25 °C	$V_{GS} = 10$ V	0.087
$Q_g$ max. (nC)	62	
$Q_{gs}$ (nC)	16	
$Q_{gd}$ (nC)	15	
Configuration	Single	

### ORDERING INFORMATION

Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SiHK100N65E-T1-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	
Continuous drain current ( $T_J = 150$ °C)	$V_{GS}$ at 10 V	$T_C = 25$ °C	A
		$T_C = 100$ °C	
Pulsed drain current <sup>a</sup>	$I_{DM}$	63	W/°C
Linear derating factor		1.47	
Single pulse avalanche energy <sup>b</sup>	$E_{AS}$	127	mJ
Maximum power dissipation	$P_D$	184	W
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	°C
Drain-source voltage slope	$dv/dt$	100	V/ns
Reverse diode $dv/dt$ <sup>c</sup>		11	


#### Notes

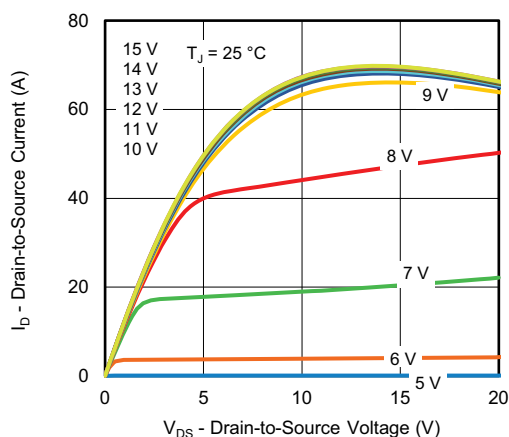
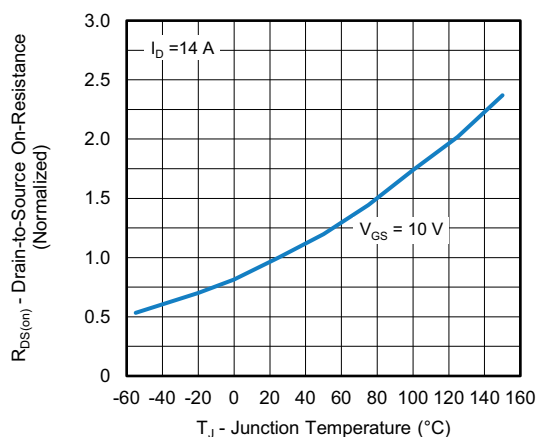
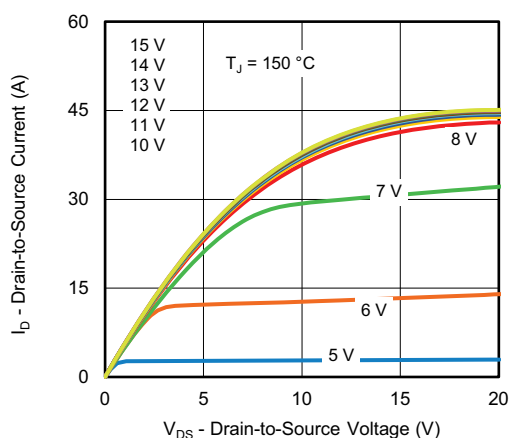
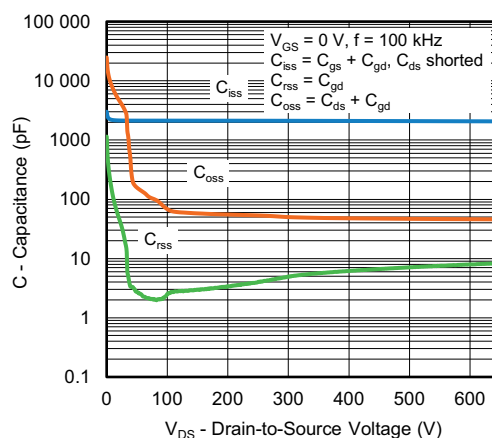
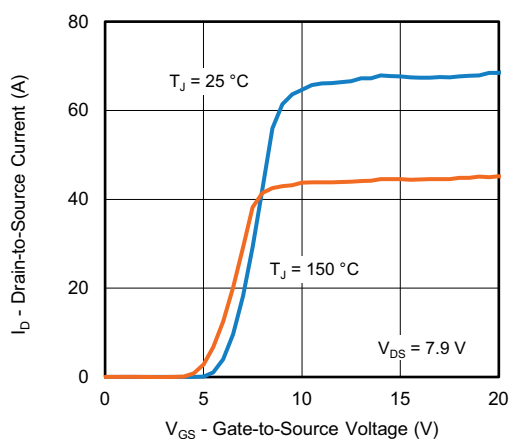
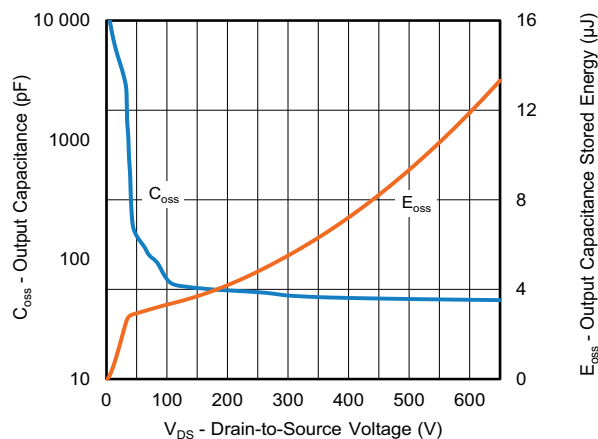
- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 140$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 3.0$  A
- $I_{SD} \leq I_D$ ,  $di/dt = 100$  A/ $\mu$ s, starting  $T_J = 25$  °C

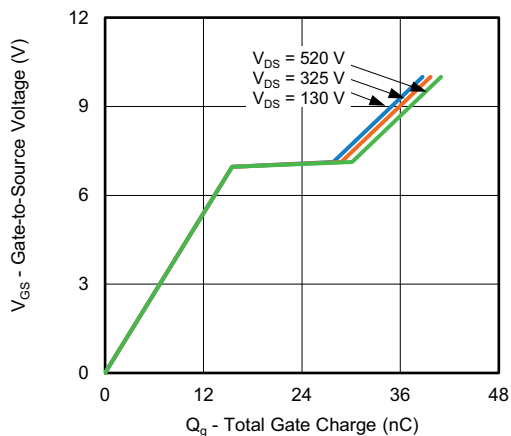
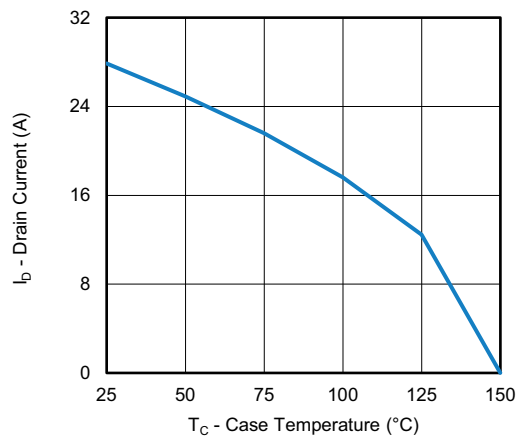
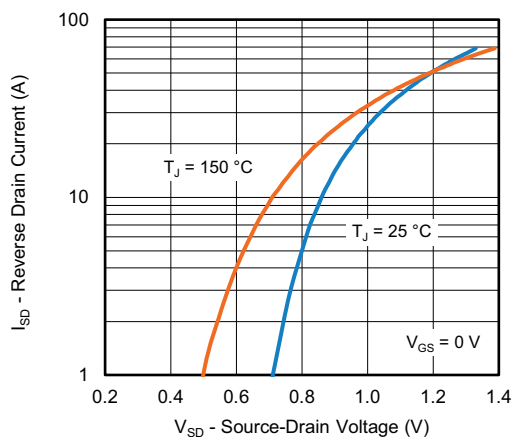
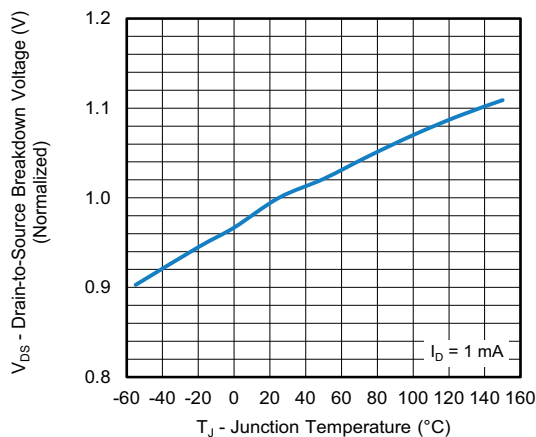
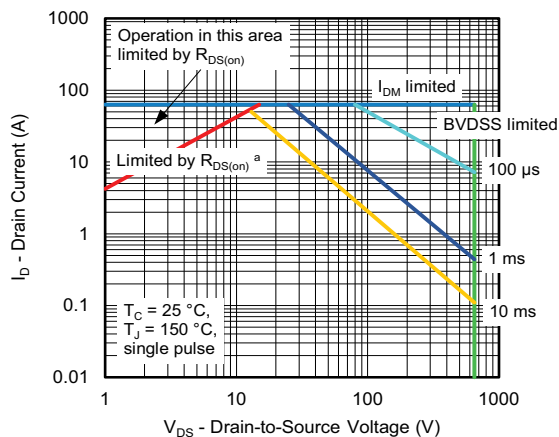
**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	40	42	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	0.51	0.68	

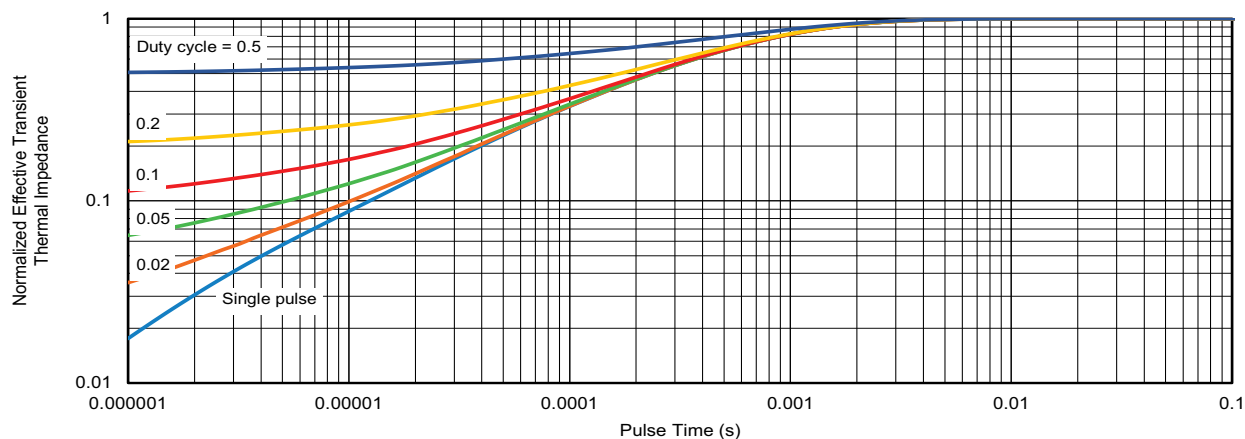
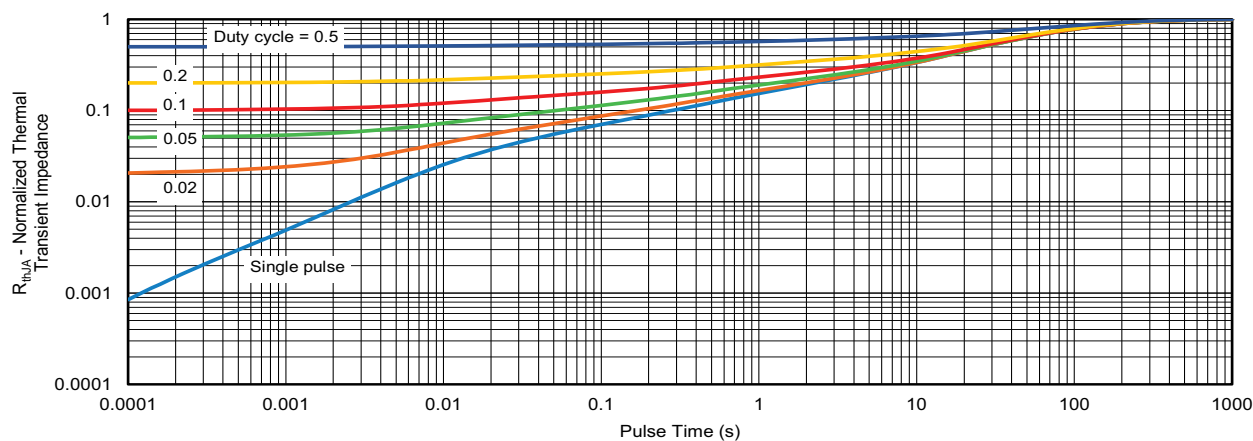
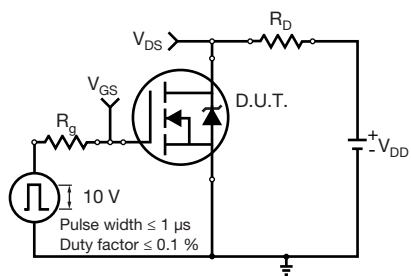
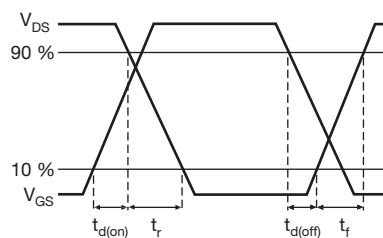
**SPECIFICATIONS** ( $T_J = 25\text{ °C}$ , unless otherwise noted)

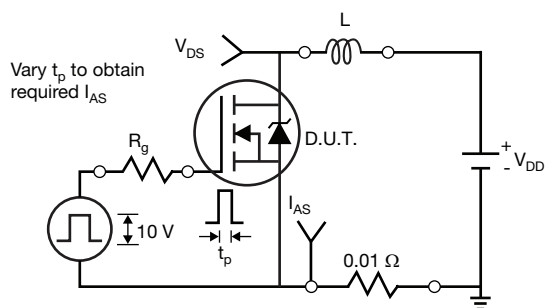
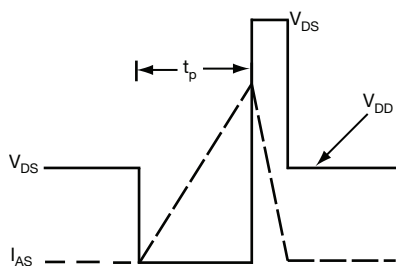
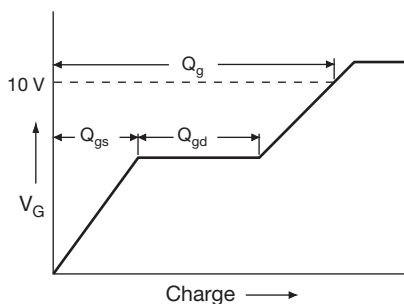
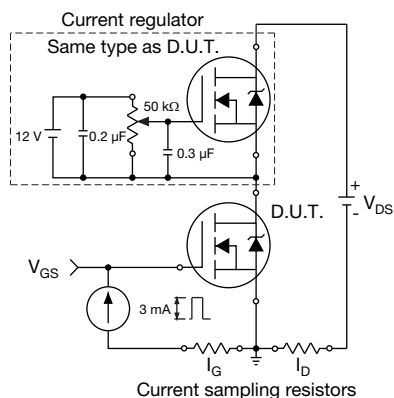
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		650	-	-	V
V <sub>DS</sub> temperature coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.68	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		3.0	-	5.0	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
		V <sub>GS</sub> = ± 30 V		-	-	± 1	μA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V		-	-	1	μA
		V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	-	10	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A	-	0.087	0.100	Ω
Forward transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 8 V, I <sub>D</sub> = 14 A		-	12	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V, f = 1 MHz		-	2137	-	pF
Output capacitance	C <sub>Oss</sub>			-	89	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	2	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>O(er)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		-	90	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>O(tr)</sub>			-	633	-	
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 14 A, V <sub>DS</sub> = 520 V	-	41	62	nC
Gate-source charge	Q <sub>gs</sub>			-	16	-	
Gate-drain charge	Q <sub>gd</sub>			-	15	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 14 A, V <sub>GS</sub> = 10 V, R <sub>g</sub> = 9.1 Ω		-	28	56	ns
Rise time	t <sub>r</sub>			-	68	136	
Turn-off delay time	t <sub>d(off)</sub>			-	50	100	
Fall time	t <sub>f</sub>			-	32	64	
Gate input resistance	R <sub>g</sub>	f = 1 MHz		0.5	1.1	2.2	Ω
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	28	A
Pulsed diode forward current	I <sub>SM</sub>			-	-	63	
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 14 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 14A, di/dt = 100 A/μs, V <sub>R</sub> = 25 V		-	362	724	ns
Reverse recovery charge	Q <sub>rr</sub>			-	5.0	10	μC
Reverse recovery current	I <sub>RRM</sub>			-	22	-	A

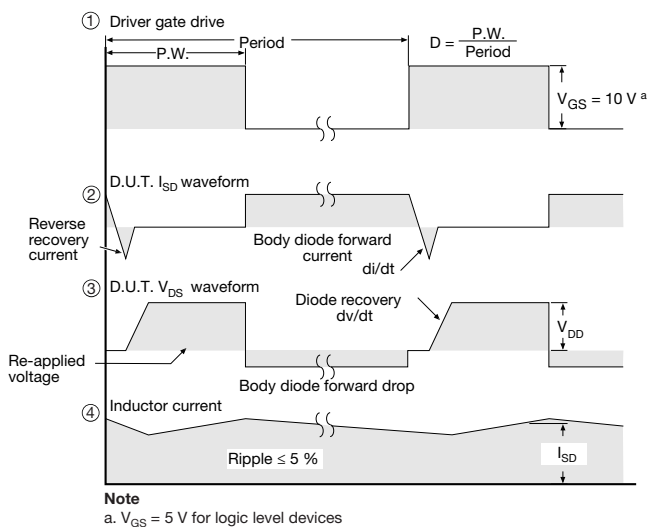
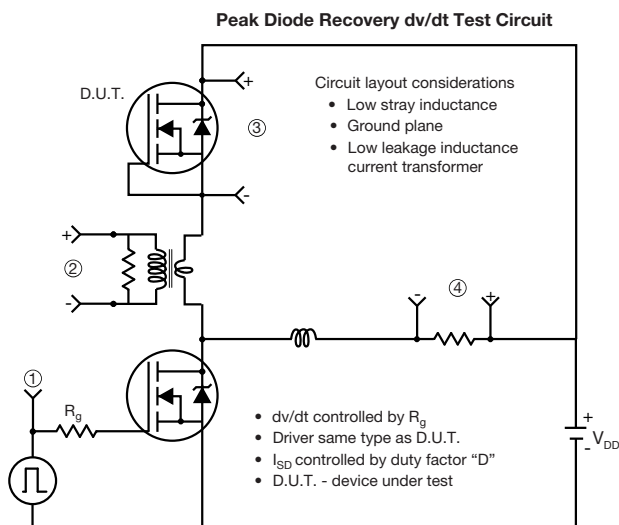
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$**


**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**

**Fig. 10 - Maximum Drain Current vs. Case Temperature**

**Fig. 8 - Typical Source-Drain Diode Forward Voltage**

**Fig. 11 - Temperature vs. Drain-to-Source Voltage**

**Fig. 9 - Maximum Safe Operating Area**
**Note**

a.  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

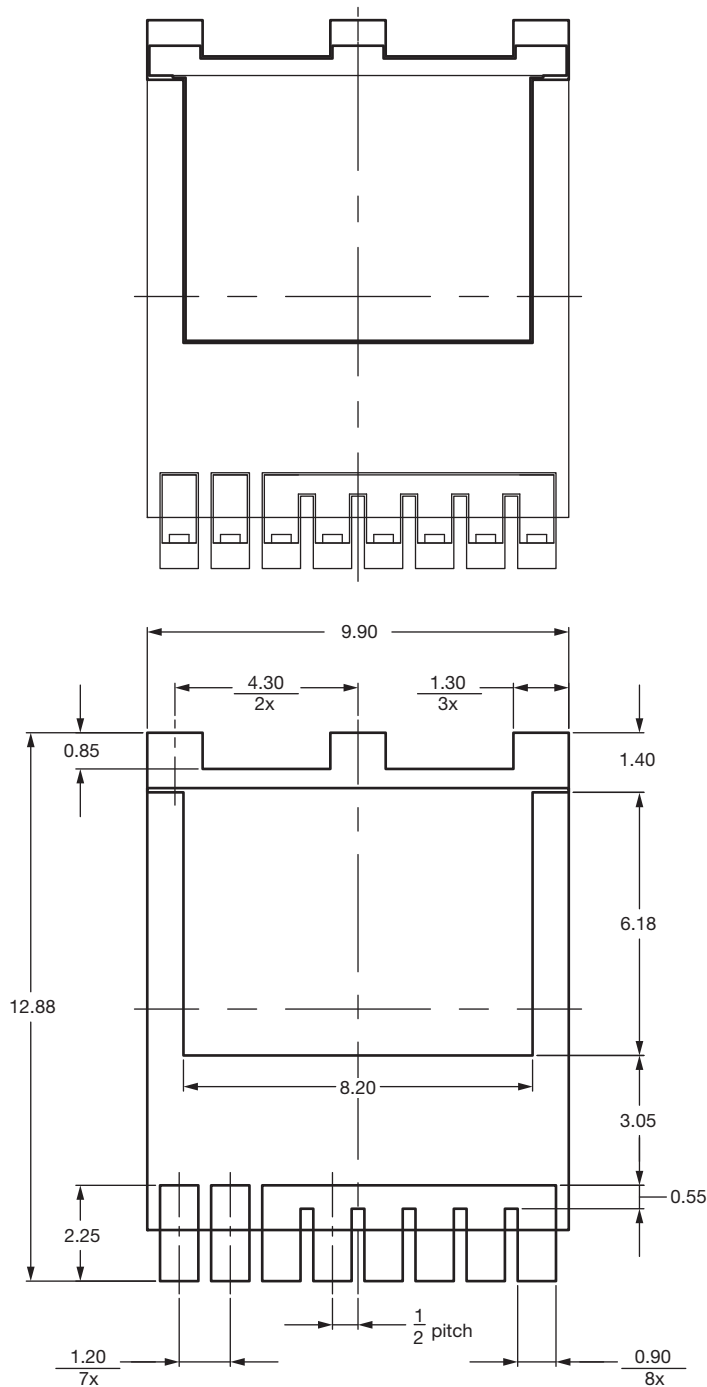

**Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case**

**Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient**

**Fig. 14 - Switching Time Test Circuit**

**Fig. 15 - Switching Time Waveforms**


**Fig. 16 - Unclamped Inductive Test Circuit**

**Fig. 17 - Unclamped Inductive Waveforms**

**Fig. 18 - Basic Gate Charge Waveform**

**Fig. 19 - Gate Charge Test Circuit**


**Fig. 20 - For N-Channel**

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## Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)


**Note**

- Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022  
DWG: 3013





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